TAZMO®



Single Wafer Cleaning System

[SSP SERIES]

Overview

The equipment was designed as precision cleaning and/or wet etching system for BEOL, FEOL 200mm, 300mm wafers. Each PM unit is isolated with bulk-head wall design controlling the atmosphere with optimum air flow. Selection of top side or top/bottom side processing capability also 2 or 4 chamber selectable.

Features

Employed multi-process cup design enablin chemical process, DI water rinsing and drying in one process chamber.

- •Chemical temperature stability is secured by the switching of circula tion of chemical module and the main tool.
- •2 fluid, mega sonic and function water cleaning capability.

Application

Silicone etching, various film removal, particle removal, metal removal, polymer removal, thin wafer process

Single Wafer Cleaning System

[SSP SERIES]

Specification

- •Single Wafer Cleaning System for φ200mm/φ300mm
- Electrode hole cleaning/ precise control etching
- Option

Use 3 chemicals for each chamber 2 Fluid nozzle system Explosion-proof specification







EFEM,Robot



TAZMO

Organic chamber

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